

April 17, 2025
AMADA CO., LTD.

Acquisition of Leading Manufacturer of PCB Drilling Machines

Co-creation of new laser machining technology
for the semiconductor industry and entry into new markets



AMADA CO., LTD. (Isehara, Kanagawa, Japan, Representative Director, President: Takaaki Yamanashi) today concluded a share transfer agreement to acquire all shares of Via Mechanics, Ltd. (Atsugi, Kanagawa, Japan, Representative Director & CEO: Hideaki Shimizu, hereafter Via Mechanics), making it a wholly-owned subsidiary.

As a result of this transfer, we aim to make a full-scale entry into the semiconductor industry by combining our laser technologies, production and supply capabilities and support framework with Via Mechanics' high-end circuit board drilling solutions and customer base. We also aim to co-create new technologies, such as laser processing and automation, and develop and launch differentiated products to meet the needs of our customers and drive technological evolution.

The AMADA Group will pursue synergies among its group companies by not only expanding existing businesses, but also by expanding into new fields such as semiconductors with the aim of achieving further growth.

■ Background and aim

The AMADA Group has set forth its "Long-Term Vision 2030" as its vision for 2030. The Group has also formulated its "Mid-Term Management Plan 2025" for the three years ending in fiscal 2025 as a concrete action plan and is currently pursuing company-wide efforts to realize that plan. In particular, we have positioned the expansion of new fields using one of our core assets, laser technology, as one of the most important initiatives in our long-term growth strategy, and we aim to expand into new, high-growth fields such as

e-Mobility, semiconductors, and medical care. The semiconductor industry in particular is experiencing rapid change, driven by the miniaturization and enhanced functions of smart devices, and a surge in demand for data centers. As a result, manufacturing processes are increasingly required to achieve rapid refinement and shorter delivery times. In response to these demands, various laser processing technologies have been garnering attention, and we have been exploring the potential of our proprietary laser technologies together with opportunities to further expand our business through M&A initiatives that leverage this technology.

Via Mechanics, a global leader in PCB drilling machines, was established as an independent company in 1968 from the Machine Tool Division of Hitachi, Ltd. In the time following, it has pursued a strategy of selecting and consolidating its business operations, evolving into a high-end manufacturer of PCB drilling machines. High-end PCBs are substrates designed for high-performance semiconductors, and in recent years have been increasingly used in semiconductors for smart devices and generative AI applications. These high-end PCBs require cutting-edge technologies to process large volumes of data at high speed and with low-power consumption. To achieve further circuit miniaturization, they demand an increase in the number and reduction in the diameter of vias, multilayered design and production in a diverse range of materials. Via Mechanics offers drilling machines equipped with ultra-high-speed spindles and high-speed, high-precision table servo technology for through-hole drilling, and laser drilling machines (CO₂ laser and UV laser systems) equipped with high-speed, high-precision galvano technology for blind hole drilling used in the PCB lamination process. Leveraging such differentiated solutions, unmatched by competitors in the field of PCB processing, Via Mechanics effectively meets the stringent demand of high-end PCBs.

We believe that our core technologies, such as laser technology, and automated equipment coupled with our flexible global production and supply framework, and IoT driven service support system are highly compatible with Via Mechanics' laser-based drilling technologies and technologies for high-speed, high-precision manufacturing equipment. Further, we anticipate strong synergies with Via Mechanics' customer base through proposals for our laser processing systems used in our micro welding business—such as wafer marking and resin mold deburring—for back-end semiconductor manufacturing processes. For these reasons, we concluded that the integration of our two companies would enable further market expansion within the semiconductor industry. By co-creating new laser processing technologies, and developing and launching differentiated products, we hope to respond to the ever-evolving technological needs of our customers more efficiently.

■ Content of the agreement

As of today, AMADA has entered into a share transfer agreement with a fund managed by Advantage Partners Inc. to acquire all of the outstanding shares of Via Mechanics held by the company. The acquisition price is 51 billion yen. The share transfer is scheduled to take

place in July 2025. Following the conclusion of the share transfer, Via Mechanics will further develop its relationship with existing customers and will contribute to them through manufacture, sell and service of its main products. Additionally, Via Mechanics will maintain its existing operations framework, and together with AMADA, efforts will be made to further enhance it.

■ Future developments

By combining the AMADA Group and Via Mechanics, we aim to provide comprehensive solutions to customers in the semiconductor industry and elsewhere. Additionally, the two companies will work together to leverage their respective sales and service networks, and technical proposal capabilities for further global expansion of the laser welding business to achieve our Long-Term Vision 2030.

By pursuing synergies among the AMADA Group companies are continuing to offer industry-leading comprehensive solutions, we aim to strengthen our group's position and achieve sustainable growth and increase corporate value.

■ Overview of Via Mechanics, Ltd.

Company name:	Via Mechanics, Ltd.
Address:	9 32 Tamura-cho, Atsugi-shi, Kanagawa-ken
Establishment:	1968
Representative:	Representative Director & CEO, Hideaki Shimizu
Description of business:	Research and development, design, manufacture, sales, and service of high-precision drill/laser processing machines for semiconductor package boards and printed circuit boards
Capital:	301 million yen
Sales revenue:	43,292 million yen (Fiscal year ended March 2024) *Consolidated
Employees:	562 persons (Fiscal year ended March 2024) *Consolidated

■ Overview of main counterparty (seller) for share acquisition

Name:	Investment Limited Partnership Advantage Partners VI, etc.
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End

* The information in this release is subject to change without notice.